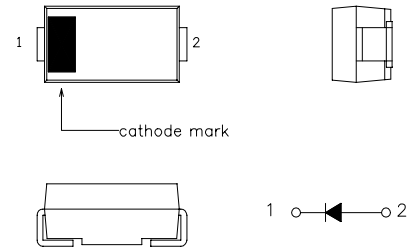


FRD Type : EC11FS4

FEATURES

- * Miniature Size, Surface Mount Device
- * Ultra-Fast Recovery
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC11FS4		Unit
Repetitive Peak Reverse Voltage	V_{RRM}	400		V
Non-repetitive Peak Reverse Voltage	V_{RSM}	440		V
Average Rectified Output Current	I_O	0.76	$T_a=25^{\circ}C$ *1	50Hz Half Sine Wave Resistive Load
		1.0	$T_a=26^{\circ}C$ *2	
RMS Forward Current	$I_{F(RMS)}$	1.57		A
Surge Forward Current	I_{FSM}	20	50Hz Half Sine Wave, 1cycle Non-repetitive	A
Operating Junction Temperature Range	T_{jw}	-40 to +150		$^{\circ}C$
Storage Temperature Range	T_{stg}	-40 to +150		$^{\circ}C$

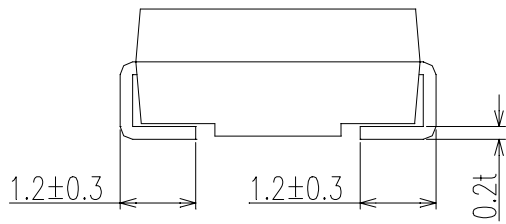
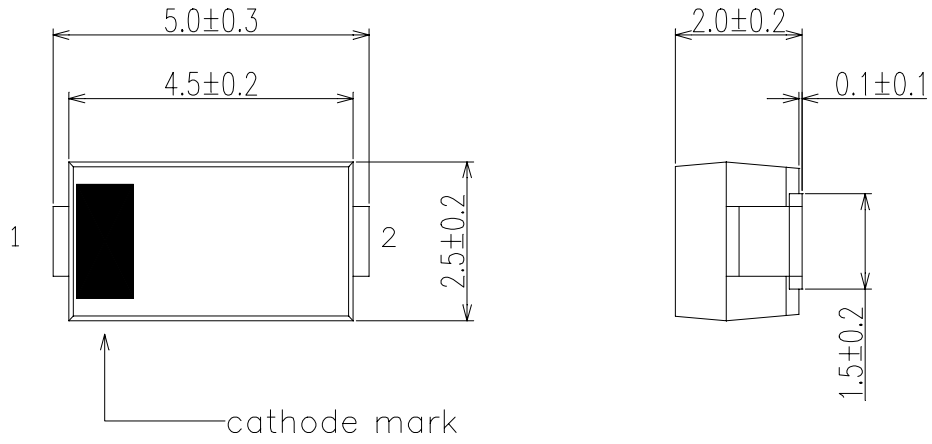
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	I_{RM}	$T_j = 25^{\circ}C, V_{RM} = V_{RRM}$	-	-	20	μA	
Peak Forward Voltage	V_{FM}	$T_j = 25^{\circ}C, I_{FM} = 1.0A$	-	-	1.25	V	
Reverse Recovery Time	trr	$I_{FM} = 1A, -di/dt = 50A/\mu s, T_a = 25^{\circ}C$	-	-	30	ns	
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	-	157	$^{\circ}C/W$
			*2	-	-	108	

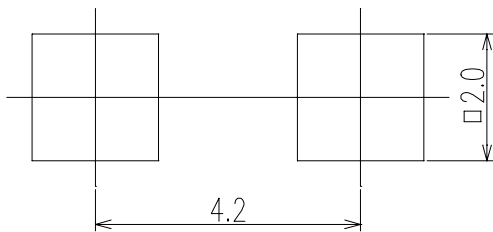
*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

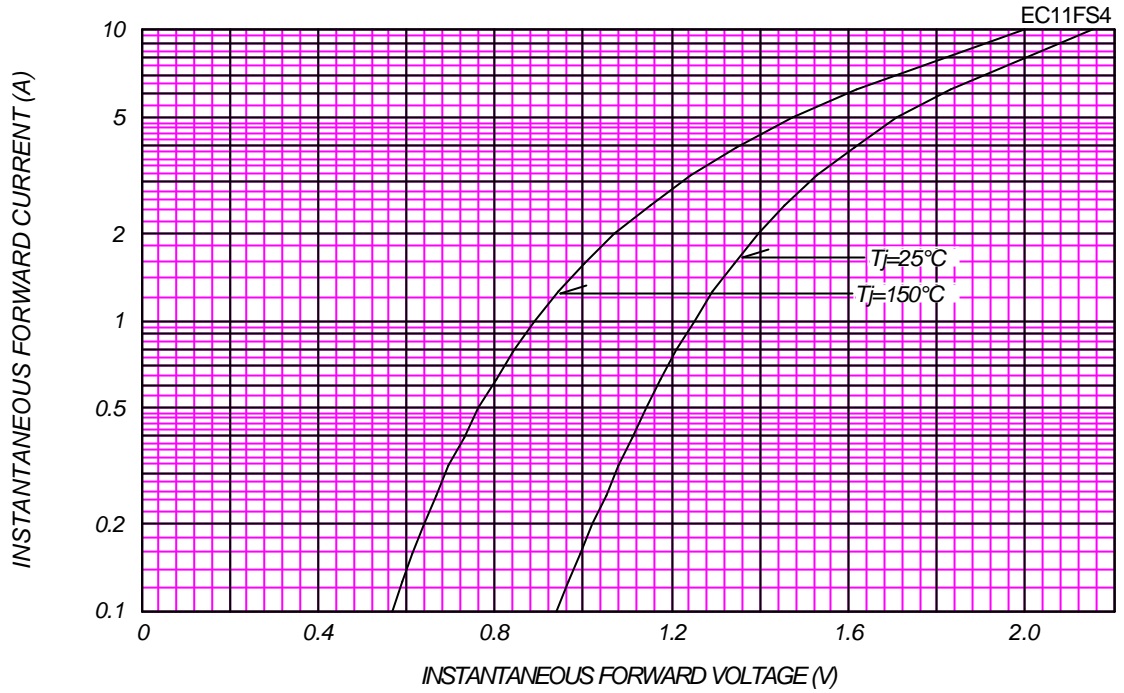
EC11FS_ OUTLINE DRAWING (Dimensions in mm)



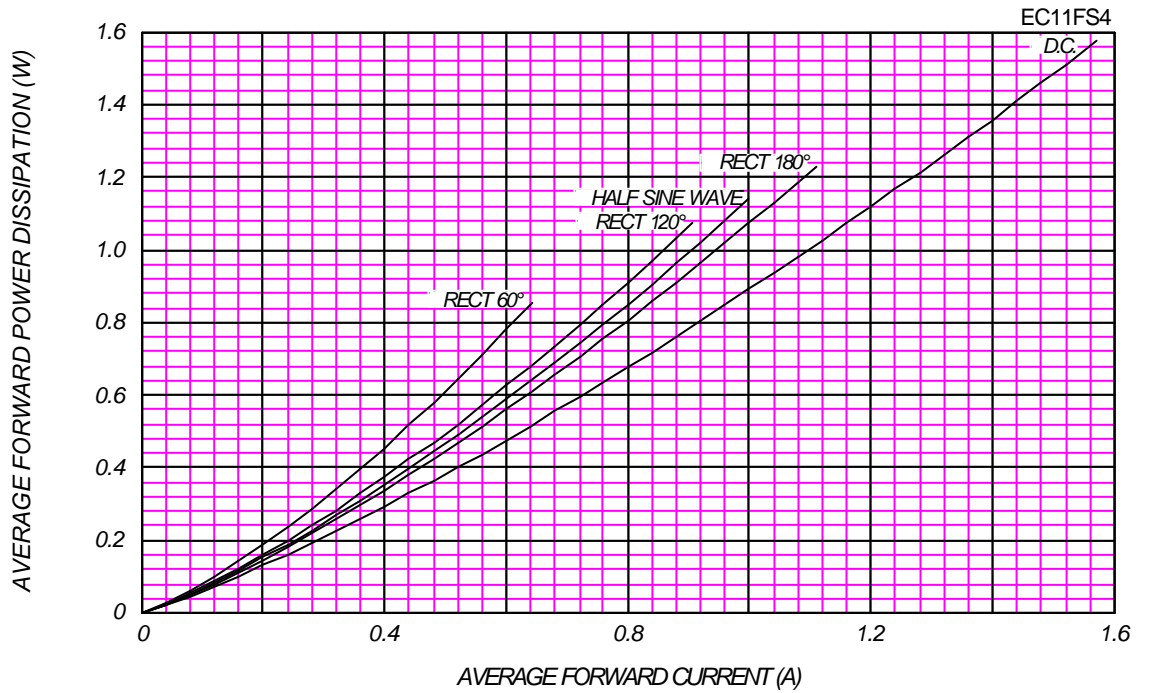
SOLDERING PAD

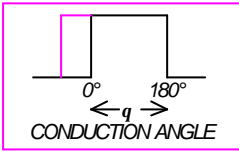


FORWARD CURRENT VS. VOLTAGE



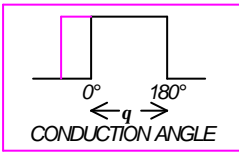
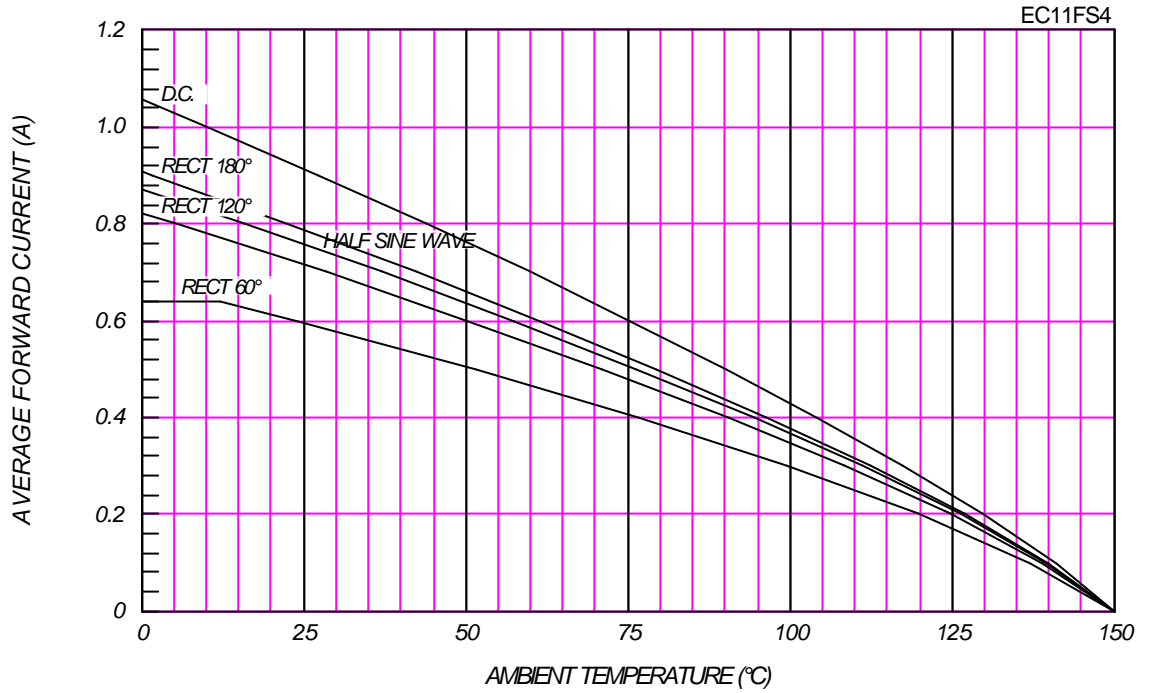
AVERAGE FORWARD POWER DISSIPATION





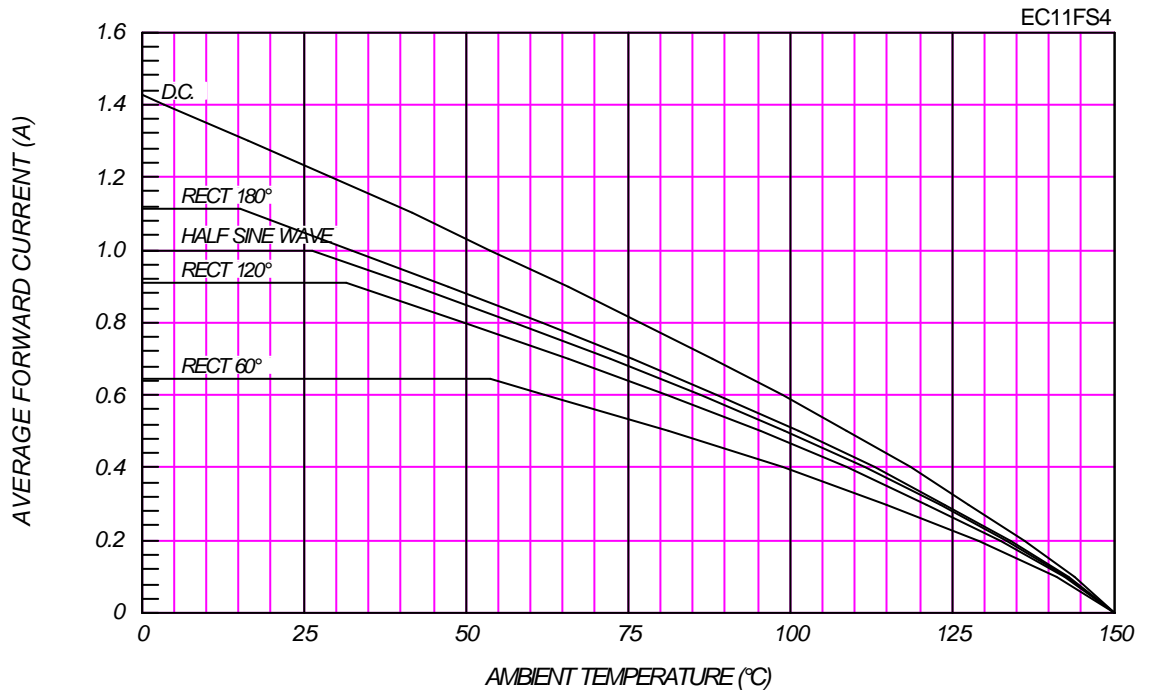
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Glass-Epoxy Substrate Mounted(Soldering Land=2x2mm)



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Alumina Substrate Mounted(Soldering Land=2x2mm)



SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

EC11FS4

